

JIS

JAPANESE INDUSTRIAL STANDARD

**Multilayer printed
wiring boards**

JIS C 5014^{—1994}

Translated and Published

by

Japanese Standards Association

**In the event of any doubt arising,
the original Standard in Japanese is to be final authority.**

1. Scope This Japanese Industrial Standard specifies multilayer printed wiring boards mainly used for electronic apparatus (hereafter referred to as "printed boards"). However, this Standard is not applicable to multilayer flexible printed wiring board, multilayer rigid to flexible printed wiring board and metal-cored printed wiring board.

Remarks: 1. The following Standards are cited in this Standard:

JIS C 5001 General rules for electronic components

JIS C 5012 Test methods for printed wiring boards

JIS C 5603 Terms and definitions for printed circuits

JIS C 6480 General rules of copper-clad laminates for printed wiring boards

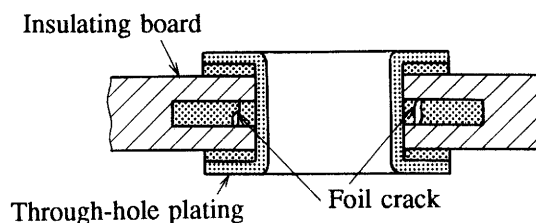
2. The International standards corresponding to this Standard are given below:

IEC 326-3 (1991) Printed boards. Part 3: Design and use of printed boards

IEC 326-6 (1980) Printed boards. Part 6: Specification for multilayer printed boards

2. Definitions For the purpose of this Standard in addition to the definitions in JIS C 5001 and JIS C 5603, the following principal definitions apply:

- (1) insertion mounting Such a mounting method that terminals of a component are inserted into component holes provided on a printed board and electrically connected.
- (2) foil crack The crack of copper foil connected with a plated-through hole that appears in the vicinity of the through-hole plating.



- (3) reference mark The mark attached to a corner of printed board for determination of correct position of the board.
- (4) component positioning mark The mark which is provided for determination of component position relative to the reference mark on a printed board.